100% Material Declaration Data Sheet FGG676

Average Weight: 3.0620 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					**0.1421**	**4.64%**
	Silicon	7440-21-3	100.00		0.1421	
Die Attach Material					**0.0124**	**0.40%**
	Silver	7440-22-4	78.00		0.0097	
	Resin	Trade Secret	22.00		0.0027	
Mold Compound					**1.0269**	**33.54%**
	Epoxy Resins	Trade Secret	12.00		0. 1232	
	SiO2	60676-86-0	88.00	Filler	0.9037	
Laminate					**1.1419**	**37.29%**
	Laminate	Trade Secret	49.15		0.5613	
	Solder Mask	Trade Secret	7.69		0.0878	
	Copper	7440-50-8	40.83	Metal Layer	0.4662	
	Nickel	7440-02-0	1.95	Metal Layer	0.0223	
	Gold	7440-57-5	0.38	Metal Layer	0.0043	
Bond Wire					**0.0235**	**0.77%**
	Gold	7440-57-5	99.00		0.023302516	
	Silver	7440-22-4	0.0025		0.000000588	
	Copper	7440-50-8	0.0005		0.000000118	
	Iron	7439-89-6	0.0005		0.000000118	
	Calcium	7440-70-2	0.0020		0.000000471	
	Palladium	7440-05-3	0.9900		0.000233025	
	Magnesium	7439-95-4	0.0005		0.000000118	
Solder Balls					**0.7153**	**23.36%**
	Tin	7440-31-5	95.50		0.6831	
	Silver	7440-22-4	4.00		0.0286	
	Copper	7440-50-8	0.50		0.0036	

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Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
3/21/06	1.0	Initial release.
5/15/06	1.1	100% Material Declaration.
9/27/06	1.2	Updated component descriptions.

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